

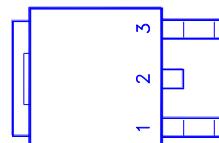
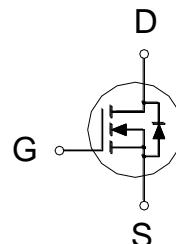
NIKO-SEM**N-Channel Enhancement Mode
Field Effect Transistor****PA910BD**

TO-252

Halogen-Free & Lead-Free

PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
100V	190mΩ	8.1A



1. GATE
2. DRAIN
3. SOURCE

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current ²	$T_C = 25^\circ\text{C}$	I_D	8.1	A
	$T_C = 100^\circ\text{C}$		5.7	
Pulsed Drain Current ¹		I_{DM}	12	
Avalanche Current		I_{AS}	2.8	
Avalanche Energy	$L = 1\text{mH}$	E_{AS}	4	mJ
Power Dissipation	$T_C = 25^\circ\text{C}$	P_D	30	W
	$T_C = 100^\circ\text{C}$		15	
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 175	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$	5	62.5	°C / W
Junction-to-Ambient	$R_{\theta JA}$			

¹Pulse width limited by maximum junction temperature.²Package limitation current is 5.3A.**ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)**

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	100			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1.3	1.9	2.3	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 80\text{V}, V_{GS} = 0\text{V}$			1	μA
		$V_{DS} = 80\text{V}, V_{GS} = 0\text{V}, T_J = 100^\circ\text{C}$			10	

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Drain-Source On-State Resistance ¹	$R_{DS(ON)}$	$V_{GS} = 10V, I_D = 3A$	143	190	$m\Omega$
		$V_{GS} = 4.5V, I_D = 3A$	153	205	
Forward Transconductance ¹	g_{fs}	$V_{DS} = 5V, I_D = 3A$	13		S
DYNAMIC					
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$	306		pF
Output Capacitance	C_{oss}		35		
Reverse Transfer Capacitance	C_{rss}		21		
Gate Resistance	R_g	$V_{GS} = 0V, V_{DS} = 0V, f = 1MHz$	2.2		Ω
Total Gate Charge ²	Q_g	$V_{DS} = 50V, V_{GS} = 10V, I_D = 3A$	8.6		nC
Gate-Source Charge ²	Q_{gs}		1		
Gate-Drain Charge ²	Q_{gd}		3.6		
Turn-On Delay Time ²	$t_{d(on)}$	$V_{DD} = 50V, I_D \geq 3A, V_{GS} = 10V, R_{GS} = 6\Omega$	10		nS
Rise Time ²	t_r		20		
Turn-Off Delay Time ²	$t_{d(off)}$		75		
Fall Time ²	t_f		22		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ C$)					
Continuous Current ³	I_S			7.4	A
Forward Voltage ¹	V_{SD}	$I_F = 3A, V_{GS} = 0V$		1.4	V
Reverse Recovery Time	t_{rr}	$I_F = 3A, dI/dt=100A/\mu s$	19		nS
Reverse Recovery Charge	Q_{rr}		10		nC

¹Pulse test : Pulse Width $\leq 300 \mu sec$, Duty Cycle $\leq 2\%$.²Independent of operating temperature.³Package limitation current is 5.3A.

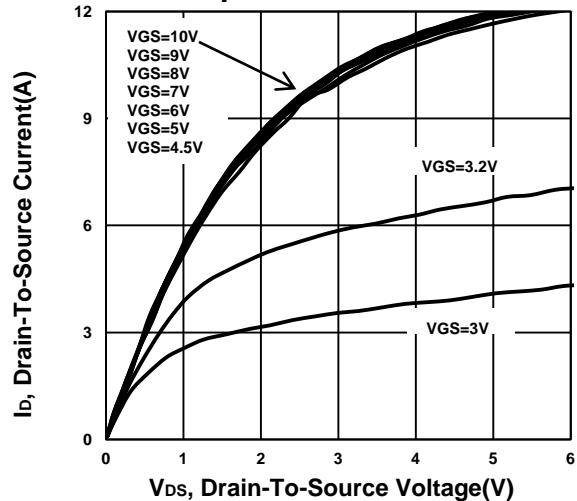
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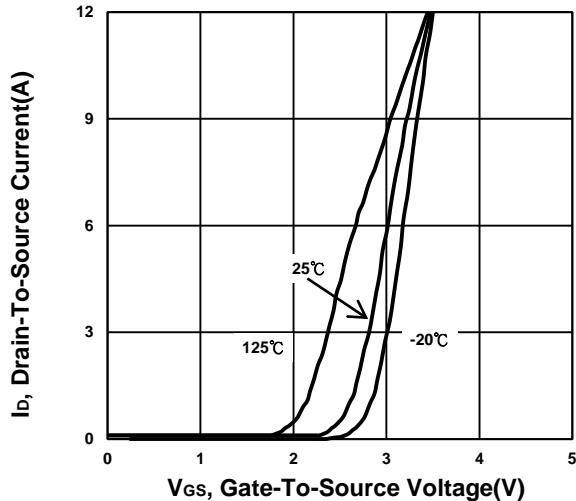
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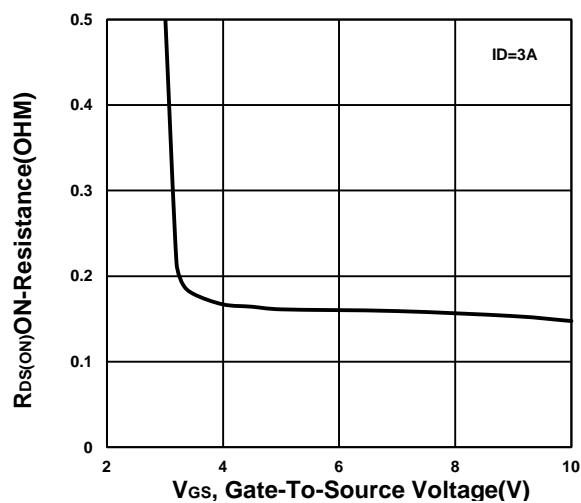
Output Characteristics



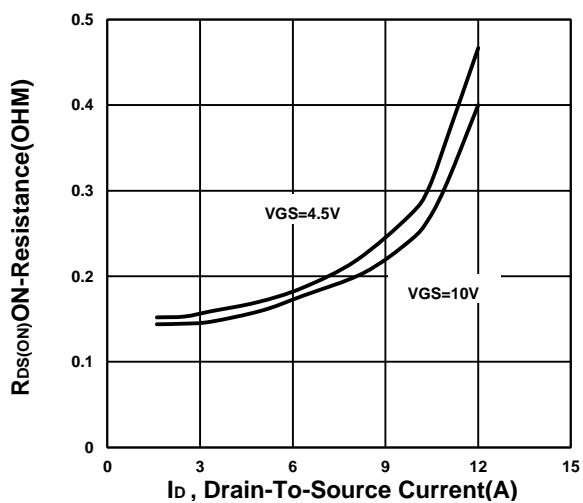
Transfer Characteristics



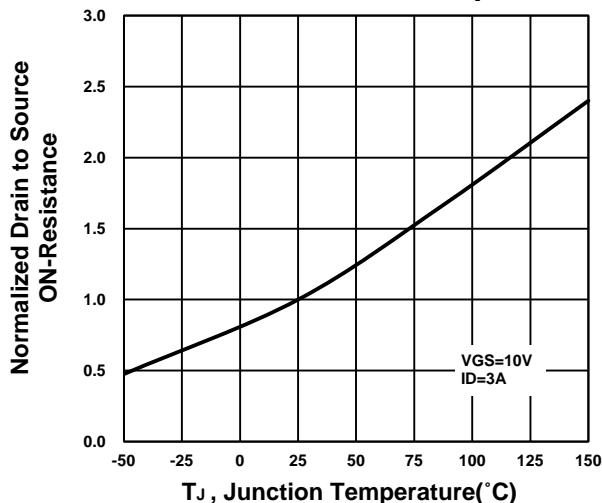
On-Resistance VS Gate-To-Source



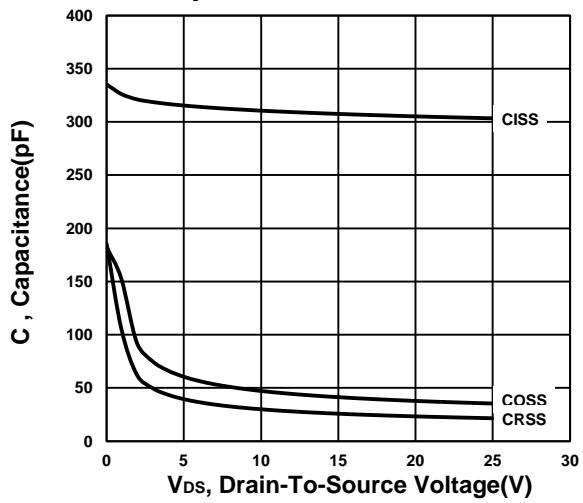
On-Resistance VS Drain Current



On-Resistance VS Temperature



Capacitance Characteristic



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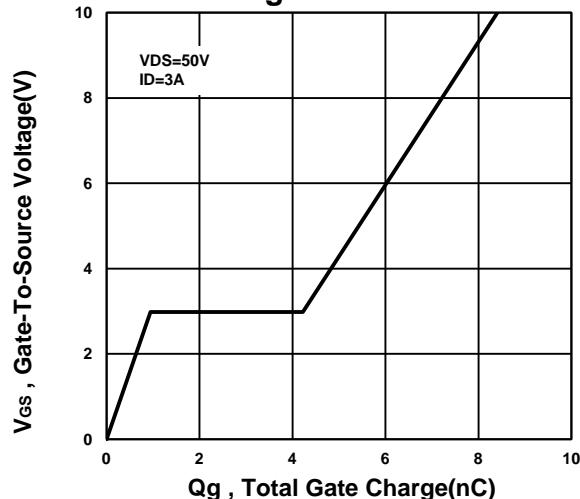
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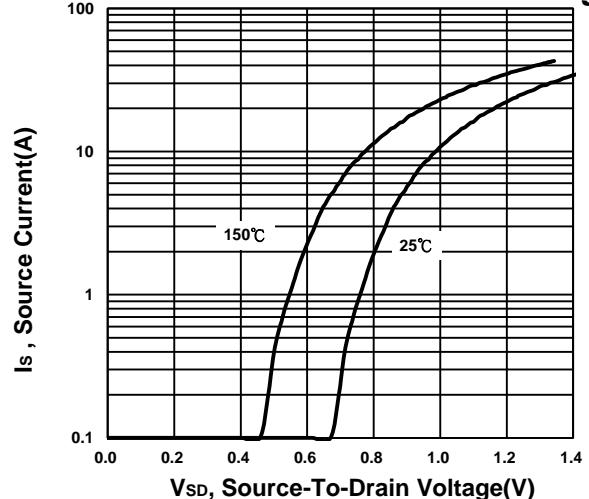
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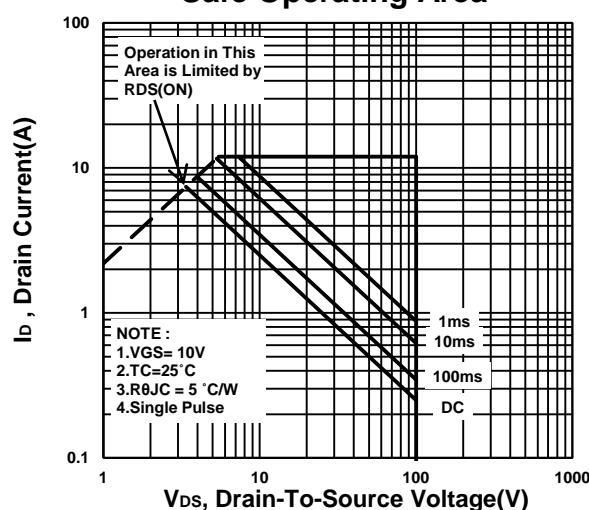
Gate charge Characteristics



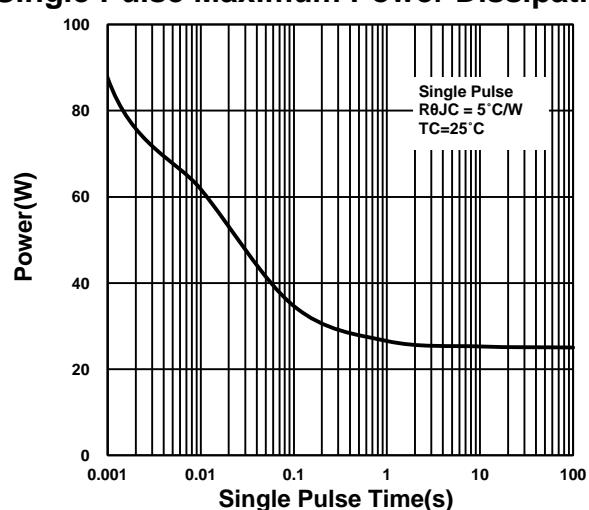
Source-Drain Diode Forward Voltage



Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve

